Electronic Acknowledgement Receipt

EFS ID:	2110955
Application Number:	10681735
International Application Number:	
Confirmation Number:	8157
Title of Invention:	SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING INVERTED LAND GRID ARRAY (LGA) PACKAGE STACKED OVER BALL GRID ARRAY (BGA) PACKAGE
First Named Inventor/Applicant Name:	Marcos Karnezos
Customer Number:	22898
Filer:	Mikio Ishimaru/Joana Gunawan
Filer Authorized By:	Mikio Ishimaru
Attorney Docket Number:	CPAC 1029-3
Receipt Date:	22-AUG-2007
Filing Date:	08-OCT-2003
Time Stamp:	13:31:44
Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	no

File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /.zip	Pages (if appl.)
1	Miscellaneous Incoming Letter	27-409-2CP_Request_Change_AttyDocketNo.pdf	37149 195081406dd522f4e9ad72b795793d9ec970fce	no	1
Warnings:					